10A*1



V_{DSS} 1200V $R_{DS(on)}$ (Typ.) 450mΩ

S2305

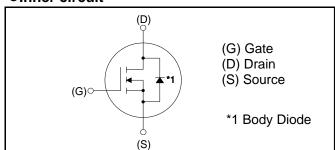
Features

- 1) Low on-resistance
- 2) Fast switching speed

 I_D

- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive

•Inner circuit



Application

- · Solar inverters
- DC/DC converters
- Switch mode power supplies
- · Induction heating
- Motor drives

● Absolute maximum ratings (T_a = 25°C)

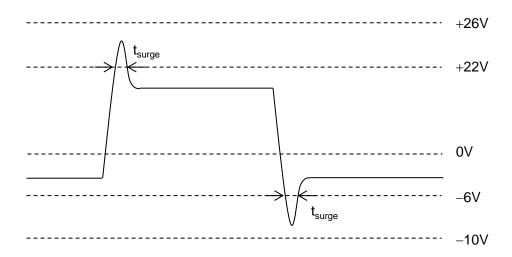
Parameter	Symbol	Value	Unit	
Drain - Source voltage		V_{DSS}	1200	V
Continuous drain current	T _c = 25°C	I _D *1	10	А
Pulsed drain current		I _{D,pulse} *2	25	А
Gate - Source voltage (DC)	V_{GSS}	-6 to 22	V	
Gate - Source surge voltage (T _{surge} < 300nsec)		V _{GSS-surge} *3	–10 to 26	V
Junction temperature		T _j	175	°C
Range of storage temperature		T _{stg}	-55 to +175	°C

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Тур.	Max.	Ullit
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	1200	-	-	V
Zero gate voltage drain current		$V_{DS} = 1200V, V_{GS} = 0V$				
	I_{DSS}	T _j = 25°C	-	1	10	μΑ
		T _j = 150°C	-	2	-	
Gate - Source leakage current	I _{GSS+}	$V_{GS} = +22V, V_{DS} = 0V$	-	-	100	nA
Gate - Source leakage current	I _{GSS-}	$V_{GS} = -6V$, $V_{DS} = 0V$	-	-	-100	nA
Gate threshold voltage	V _{GS (th)}	$V_{DS} = V_{GS}$, $I_D = 0.9 \text{mA}$	1.6	2.8	4.0	V
Static drain - source on - state resistance		$V_{GS} = 18V, I_D = 3A$				
	R _{DS(on)} *4	T _j = 25°C	-	450	556	mΩ
		T _j = 125°C	-	610	-	
Gate input resistance	R _G	f = 1MHz, open drain	-	25	-	Ω

^{*1} Limited only by maximum temperature allowed.

^{*3} Example of acceptable Vgs waveform



*4 Pulsed

^{*2} PW \leq 10 $\mu s,$ Duty cycle \leq 1%

●Electrical characteristics (T_a = 25°C)

Doromotor	Cumbal	Conditions	Values			Linit
Parameter	Symbol		Min.	Тур.	Max.	Unit
Transconductance	g _{fs} *4	$V_{DS} = 10V, I_{D} = 3A$	-	1.0	-	S
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	463	-	
Output capacitance	C _{oss}	V _{DS} = 800V	-	21	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	4	-	
Effective output capacitance, energy related	C _{o(er)}	$V_{GS} = 0V$ $V_{DS} = 0V$ to 500V	-	31	-	pF
Turn - on delay time	t _{d(on)} *4	$V_{DD} = 400V, V_{GS} = 18V$	ı	19	ı	
Rise time	t _r *4	I _D = 3A	ı	17	ı	nc
Turn - off delay time	t _{d(off)} *4	$R_L = 133\Omega$	ı	38	ı	ns
Fall time	t _f *4	$R_G = 0\Omega$	ı	34	ı	
Turn - on switching loss	E _{on} *4	$V_{DD} = 600V, I_{D} = 3A$ $V_{GS} = 18V/0V$	-	47	-	1
Turn - off switching loss	E _{off} *4	$R_G = 0\Omega$, L=500 μ H * E_{on} includes diode reverse recovery	-	17	-	μJ

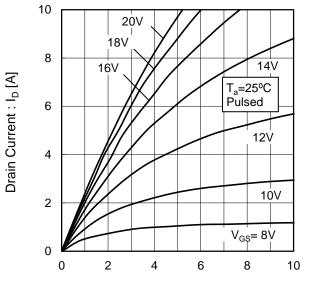
•Gate Charge characteristics $(T_a = 25^{\circ}C)$

Parameter	Symbol	Conditions	Values			Unit
			Min.	Тур.	Max.	Offic
Total gate charge	Qg *4	V _{DD} = 400V	-	27	-	
Gate - Source charge	Q _{gs} *4	$I_D = 3A$	-	7	-	nC
Gate - Drain charge	Q _{gd} *4	V _{GS} = 18V	ı	9	ı	
Gate plateau voltage	V _(plateau)	$V_{DD} = 400V, I_{D} = 3A$	-	10.5	ı	V

ullet Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

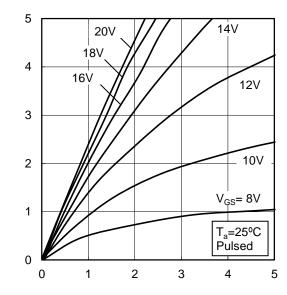
Parameter	Symbol	Conditions	Values			Unit
			Min.	Тур.	Max.	Unit
Inverse diode continuous, forward current	l _S *1	T _c = 25°C	1	ı	10	А
Inverse diode direct current, pulsed	I _{SM} *2		-	-	25	А
Forward voltage	V _{SD} *4	$V_{GS} = 0V$, $I_S = 3A$	-	4.3	-	V
Reverse recovery time	t _{rr} *4	I _F = 3A, V _R = 400V di/dt = 110A/μs	ı	19	ı	ns
Reverse recovery charge	Q _{rr} *4		-	13	-	nC
Peak reverse recovery current	I _{rrm} *4		-	1.4	-	Α

Fig.1 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.2 Typical Output Characteristics(II)

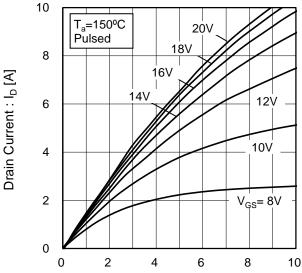


Drain Current: I_D [A]

Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

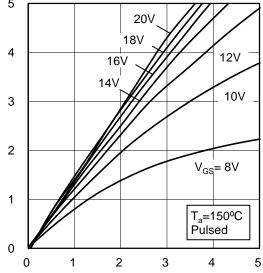
Fig.3 T_j = 150°C Typical Output
Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

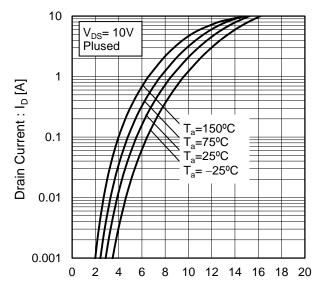
Fig.4 T_j = 150°C Typical Output
Characteristics(II)

5



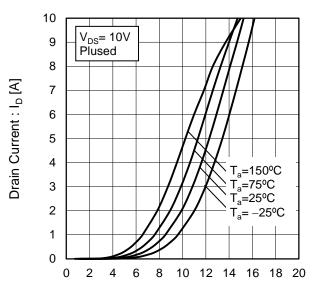
Drain - Source Voltage : V_{DS} [V]

Fig.5 Typical Transfer Characteristics (I)



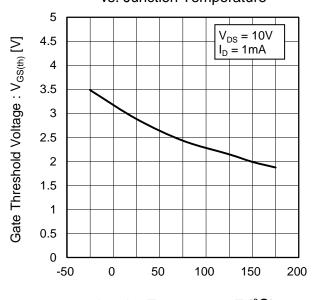
Gate - Source Voltage : V_{GS} [V]

Fig.6 Typical Transfer Characteristics (II)



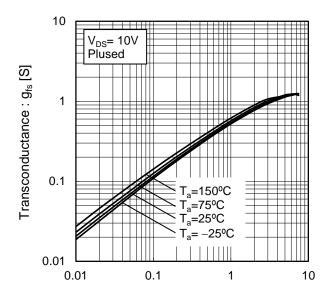
Gate - Source Voltage : V_{GS} [V]

Fig.7 Gate Threshold Voltage vs. Junction Temperature



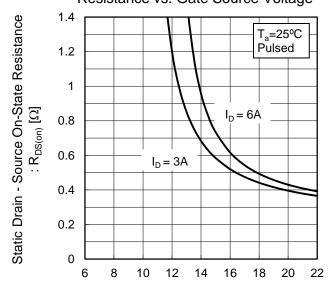
Junction Temperature : T_j [°C]

Fig.8 Transconductance vs. Drain Current



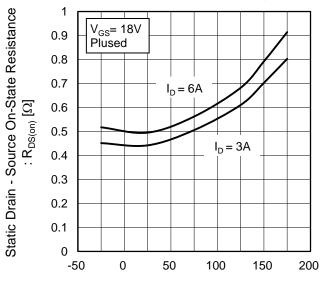
Drain Current : I_D [A]

Fig.9 Static Drain - Source On - State Resistance vs. Gate Source Voltage



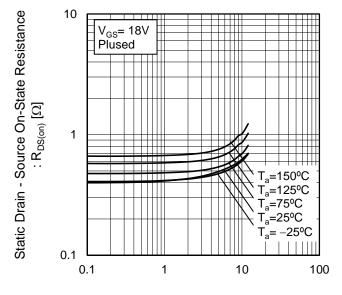
Gate - Source Voltage : V_{GS} [V]

Fig.10 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature : T_i [°C]

Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

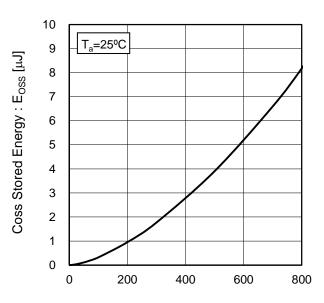


Drain Current : I_D [A]

Fig.12 Typical Capacitance vs. Drain - Source Voltage $\begin{array}{c} 10000 \\ \hline \\ 1000 \\ \hline \\ O \\ \end{array}$

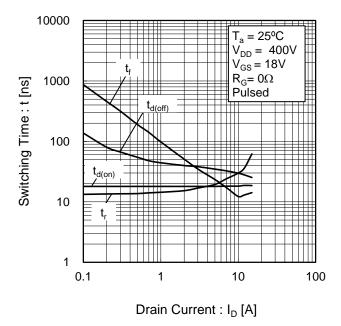
Drain - Source Voltage : V_{DS} [V]

Fig.13 Coss Stored Energy



Drain - Source Voltage : V_{DS} [V]

Fig.14 Switching Characteristics



Gate - Source Voltage : V_{GS} [V]

20 $= 25^{\circ}C$ V_{DD}= 400V $I_D = 3A$ Pulsed 15 10 5 0 5 0 10 15 20 25 30

Fig.15 Dynamic Input Characteristics

Total Gate Charge : Q_g [nC]

50

40

30 20

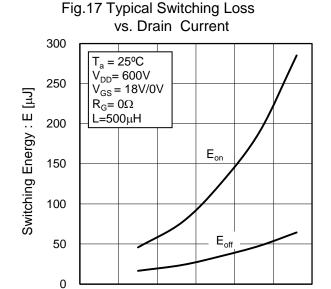
10 0

•Electrical characteristic curves

Fig.16 Typical Switching Loss vs. Drain - Source Voltage 100 $T_a = 25^{\circ}C$ 90 $I_D = 3A$ $V_{GS} = 18V/0V$ 80 Switching Energy : $E[\mu J]$ $R_G = 0\Omega$ 70 L=500μH E_{on} 60

0 200 400 600 800 1000

Drain - Source Voltage : V_{DS} [V]



0

2

Drain Current : I_D [A]

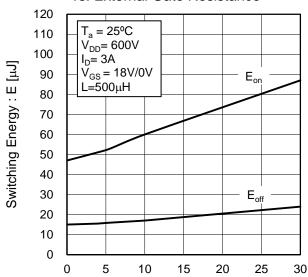
6

8

10

12

Fig.18 Typical Switching Loss vs. External Gate Resistance



External Gate Resistance : $R_G[\Omega]$

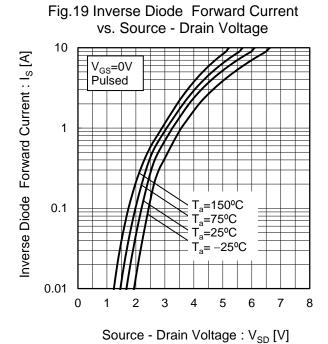


Fig. 20 Reverse Recovery Time
vs. Inverse Diode Forward Current

1000

T_a=25°C
di / dt = 110A / μs
V_R = 400V
V_{SS} = 0V
Pulsed

100
1 100

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

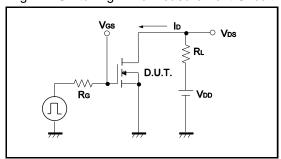


Fig.2-1 Gate Charge Measurement Circuit

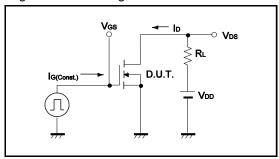


Fig.3-1 Switching Energy Measurement Circuit

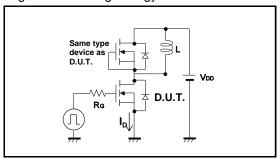


Fig.4-1 Reverse Recovery Time Measurement Circuit Fig.4-2 Reverse Recovery Waveform

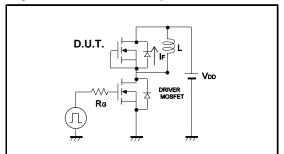


Fig.1-2 Switching Waveforms

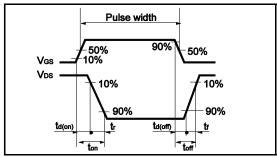


Fig.2-2 Gate Charge Waveform

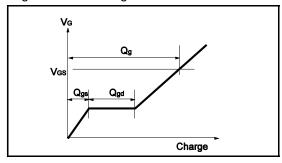
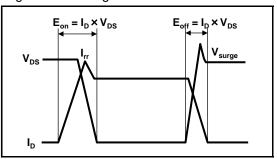
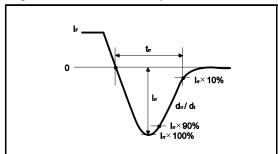


Fig.3-2 Switching Waveforms





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